



Receipt
2FE1

#8 CFR
6-11-03
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

FILE COPY

In re PATENT application of)
Osamu NAKAMURA et al.)
Serial No. 10/056,055)
Filed: January 28, 2002)
For: SEMICONDUCTOR DEVICE AND)
MANUFACTURING METHOD OF)
THE SAME)

Attn: Customer Correction Branch

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with The United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20131, on 7/26/02

Attention: Application Processing Division

REQUEST FOR CORRECTED FILING RECEIPT

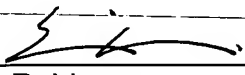
Honorable Commissioner of Patents
Washington, D.C 20231

Sir:

The Filing Receipt received in the above-identified application has errors thereon due to Patent Office error as shown in red on the attached copy.

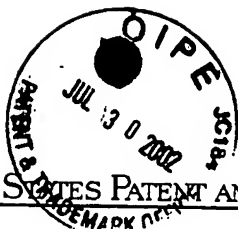
In view of the above, it is requested that a Corrected Filing Receipt be issued.

Respectfully submitted,


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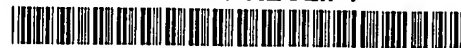
APPLICATION NUMBER	FILING DATE	GRP ART UNIT	TO 2-2-2002 MAIL ROOM	ATTY. DOCKET NO.	DRAWINGS	TOT CLAIMS	IND CLAIMS
10/056,055	01/28/2002	2811	2622	-0756-2429	24	80	11

0756-2428

31780
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CONFIRMATION NO. 3986

UPDATED FILING RECEIPT



OC00000008176732

Date Mailed: 05/23/2002

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Filing Receipt Corrections, facsimile number 703-746-9195. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

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Domestic Priority data as claimed by applicant

Foreign Applications

JAPAN 2001-019367 01/29/2001

If Required, Foreign Filing License Granted 03/01/2002

Projected Publication Date: 08/29/2002

N n-Publication Request: No

Early Publication Request: No

Title

Semiconductor device and manufacturing method of the same